



No. 135

**City University of Hong Kong – Centre for Electronic Packaging and Assemblies,
Failure Analysis and Reliability Engineering (EPA Centre)**

香港城市大學 – 電子封製及組裝暨失效分析及可靠性工程中心

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CLIENTELE : Public
服務對象 公眾

ACCREDITED TEST : Chemical Testing 化學測試
CATEGORIES Electrical and Electronic Products 電氣及電子產品
認可測試類別 Physical and Mechanical Testing 物理及機械測試

SCOPE OF : As shown on the following pages 詳見後頁
ACCREDITATION
認可範圍

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TEST CATEGORY 測試類別	ITEMS, MATERIALS OR PRODUCTS TESTED 測試項目、材料或產品	SPECIFIC TESTS OR PROPERTIES MEASURED 特定測試或量度的特性	SPECIFICATION, STANDARD METHOD OR TECHNIQUE USED 規範、標準方法或應用技術
CHEMICAL TESTING 化學測試	Circuit boards	Chemical tests:- Anionic contaminants :- - Chloride - Fluoride - Bromide - Nitrite - Nitrate - Phosphate - Sulphate (excluding weak organic acid anions) Cation contaminants :- - Ammonium - Calcium - Sodium - Magnesium - Potassium (excluding Lithium cation)	The Institute for Interconnecting and Packaging Electronic Circuits, Test Method Manual, IPC – TM – 650, Number 2.3.28, Date 05/04 Ionic Analysis of Circuit Boards, Ion Chromatography Method

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ELECTRICAL and ELECTRONIC PRODUCTS 電氣及電子產品	Printed circuit boards and related solder mask	Product performance tests :- - Measurement of moisture and insulation resistance	The Institute for Interconnecting and Packaging Electronic Circuits Test Methods Manual IPC-TM-650 Number 2.6.3 Rev. F (5/04) <i>< excluding the following ></i> Method A (testing with conformal coating) and Number 2.6.3.1 Rev. E (03/07) <i>< excluding the following ></i> Clauses 5.3.1 to first sentence of 5.3.4 (preparation of sample board)

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PHYSICAL and MECHANICAL TESTING 物理及機械測試	Metallic coatings	Coating thickness measurement: - - Scanning Electron Microscopy (0.5 μ m – 10 μ m)	ASTM B748-90 (Reapproved 2006)